

ETD 49/25/16 Core and accessories

Series/Type: B66367, B66368

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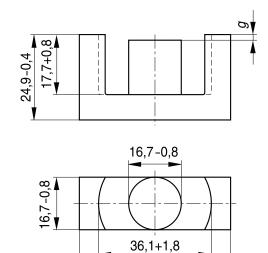
Core B66367

- To IEC 61185
- For SMPS transformers with optimum weight/performance ratio at small volume
- Delivery mode: single units

Magnetic characteristics (per set)

 $\Sigma I/A = 0.54 \text{ mm}^{-1}$ $I_e = 114 \text{ mm}$ $A_e = 211 \text{ mm}^2$ $A_{min} = 209 \text{ mm}^2$ $V_e = 24100 \text{ mm}^3$

Approx. weight 124 g/set



 $48,5^{+1,3}_{-0.9}$

FEK0061-Y

Ungapped

Material	A _L value nH	μ_{e}	B _S * mT	P _V W/set	Ordering code
N27	3700 +30/–20%	1590	320	< 4.59 (200 mT, 25 kHz, 100 °C)	B66367G0000X127
N87	3800 +30/–20%	1630	320	< 12.40 (200 mT, 100 kHz, 100 °C)	B66367G0000X187
N97	3900 +30/–20%	1680	320	< 10.60 (200 mT, 100 kHz, 100 °C)	B66367G0000X197

^{*} H = 250 A/m; f = 10 kHz; T = 100 °C

Gapped

Material	g mm	A _L value approx. nH	μ_{e}	Ordering code ** = 27 (N27) = 87 (N87)
N27,	0.20 ±0.02	1035	444	B66367G0200X1**
N87	0.50 ±0.05	525	225	B66367G0500X1**
	1.00 ±0.05	314	135	B66367G1000X1**
	2.00 ±0.05	188	81	B66367G2000X1**

The A_L value in the table applies to a core set comprising one ungapped core (dimension g=0) and one gapped core (dimension g>0).



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Core B66367

Calculation factors (for formulas, see "E cores: general information")

Material	Relationship air gap – A _L v		Calculation o	f saturation cu	rrent	
	K1 (25 °C)	K2 (25 °C)	K3 (25 °C)	K4 (25 °C)	K3 (100 °C)	K4 (100 °C)
N27	314	-0.741	504	-0.847	470	-0.865
N87	314	-0.741	485	-0.796	460	-0.873

Validity range: K1, K2: 0.10 mm < s < 3.50 mm

K3, K4: 120 nH < A_L < 1160 nH



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Accessories B66368

Coil former

Material: GFR polyterephthalate, UL 94 V-0, insulation class to IEC 60085:

Valox 420-SE0® [E45329 (M)], GE PLASTICS B V

Solderability: to IEC 60068-2-20, test Ta, method 1 (aging 3): 235 °C, 2 s

Resistance to soldering heat: to IEC 60068-2-20, test Tb, method 1B: 350 °C, 3.5 s

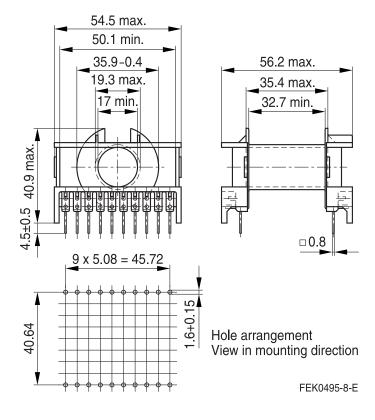
Winding: see Data Book 2013, chapter "Processing notes, 2.1"

Yoke

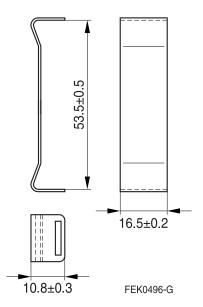
Material: Stainless spring steel (0.4 mm)

Coil former					Ordering code
Sections	A _N mm ²	I _N mm	A_R value $\mu\Omega$	Pins	
1	269.4	86	11	20	B66368B1020T001 B66368W1020T001
Yoke (order	ing code pe	r piece, 2 are	required)		B66368A2000X000

Coil former



Yoke





Cautions and warnings

Mechanical stress and mounting

Ferrite cores have to meet mechanical requirements during assembling and for a growing number of applications. Since ferrites are ceramic materials one has to be aware of the special behavior under mechanical load.

As valid for any ceramic material, ferrite cores are brittle and sensitive to any shock, fast changing or tensile load. Especially high cooling rates under ultrasonic cleaning and high static or cyclic loads can cause cracks or failure of the ferrite cores.

For detailed information see chapter "Definitions", section 8.1.

Effects of core combination on A₁ value

Stresses in the core affect not only the mechanical but also the magnetic properties. It is apparent that the initial permeability is dependent on the stress state of the core. The higher the stresses are in the core, the lower is the value for the initial permeability. Thus the embedding medium should have the greatest possible elasticity.

For detailed information see chapter "Definitions", section 8.2.

Heating up

Ferrites can run hot during operation at higher flux densities and higher frequencies.

NiZn-materials

The magnetic properties of NiZn-materials can change irreversible in high magnetic fields.

Processing notes

- The start of the winding process should be soft. Else the flanges may be destroid.
- To strong winding forces may blast the flanges or squeeze the tube that the cores can no more be mount.
- To long soldering time at high temperature (>300 °C) may effect coplanarity or pin arrangement.
- Not following the processing notes for soldering of the J-leg terminals may cause solderability problems at the transformer because of pollution with Sn oxyd of the tin bath or burned insulation of the wire. For detailed information see chapter "Processing notes", section 8.2.
- The dimensions of the hole arrangement have fixed values and should be understood as a recommendation for drilling the printed circuit board. For dimensioning the pins, the group of holes can only be seen under certain conditions, as they fit into the given hole arrangement. To avoid problems when mounting the transformer, the manufacturing tolerances for positioning the customers' drilling process must be considered by increasing the hole diameter.



Symbols and terms

Symbol	Meaning	Unit
A	Cross section of coil	mm ²
A_{e}	Effective magnetic cross section	mm ²
A_L	Inductance factor; $A_L = L/N^2$	nH
A_{L1}	Minimum inductance at defined high saturation ($= μ_a$)	nH
A _{min}	Minimum core cross section	mm ²
A _N	Winding cross section	mm ²
A_R	Resistance factor; $A_R = R_{Cu}/N^2$	$\mu\Omega = 10^{-6} \Omega$
В	RMS value of magnetic flux density	Vs/m², mT
ΔΒ	Flux density deviation	Vs/m², mT
Ê	Peak value of magnetic flux density	Vs/m², mT
ΔÂ	Peak value of flux density deviation	Vs/m², mT
B_DC	DC magnetic flux density	Vs/m², mT
B_R	Remanent flux density	Vs/m², mT
B_S	Saturation magnetization	Vs/m², mT
C_0	Winding capacitance	F = As/V
CDF	Core distortion factor	mm ^{-4.5}
DF	Relative disaccommodation coefficient DF = d/μ_i	
d	Disaccommodation coefficient	
E_a	Activation energy	J
f	Frequency	s−1, Hz
f _{cutoff}	Cut-off frequency	s ^{−1} , Hz
f _{max}	Upper frequency limit	s−1, Hz
f_{min}	Lower frequency limit	s ^{−1} , Hz
f _r	Resonance frequency	s ^{−1} , Hz
f_{Cu}	Copper filling factor	
g	Air gap	mm
Н	RMS value of magnetic field strength	A/m
Ĥ	Peak value of magnetic field strength	A/m
H_{DC}	DC field strength	A/m
H_c	Coercive field strength	A/m
h	Hysteresis coefficient of material	10 ⁻⁶ cm/A
h/μ_i^2	Relative hysteresis coefficient	10 ⁻⁶ cm/A
I	RMS value of current	Α
I_{DC}	Direct current	Α
Î	Peak value of current	Α
J	Polarization	Vs/m ²
k	Boltzmann constant	J/K
k_3	Third harmonic distortion	
k _{3c}	Circuit third harmonic distortion	
L	Inductance	H = Vs/A



Symbols and terms

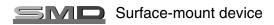
Symbol	Meaning	Unit
ΔL/L	Relative inductance change	Н
L_0	Inductance of coil without core	Н
L _H	Main inductance	Н
L_p	Parallel inductance	Н
L _{rev}	Reversible inductance	Н
Ls	Series inductance	Н
l _e	Effective magnetic path length	mm
I _N	Average length of turn	mm
N	Number of turns	
P_{Cu}	Copper (winding) losses	W
P _{trans}	Transferrable power	W
P_V	Relative core losses	mW/g
PF	Performance factor	
Q	Quality factor (Q = $\omega L/R_s$ = 1/tan δ_L)	
R	Resistance	Ω
R_{Cu}	Copper (winding) resistance (f = 0)	Ω
R_h	Hysteresis loss resistance of a core	Ω
ΔR_h	R _h change	Ω
R _i	Internal resistance	Ω
R_p	Parallel loss resistance of a core	Ω
R_s^r	Series loss resistance of a core	Ω
R_{th}	Thermal resistance	K/W
R_V	Effective loss resistance of a core	Ω
S	Total air gap	mm
Τ	Temperature	°C
ΔT	Temperature difference	K
T_{C}	Curie temperature	°C
t	Time	s
t_{v}	Pulse duty factor	
tan δ	Loss factor	
tan δ_L	Loss factor of coil	
tan δ_r	(Residual) loss factor at $H \rightarrow 0$	
tan δ_e	Relative loss factor	
$tan \delta_h$	Hysteresis loss factor	
tan δ/μ _i	Relative loss factor of material at $H \rightarrow 0$	
U	RMS value of voltage	V
Û	Peak value of voltage	V
V _e	Effective magnetic volume	mm ³
z	Complex impedance	Ω
Z_n	Normalized impedance $ Z _n = Z /N^2 \times \varepsilon (_e/A_e)$	Ω/mm



Symbols and terms

Symbol	Meaning	Unit
α	Temperature coefficient (TK)	1/K
α_{F}	Relative temperature coefficient of material	1/K
α_{e}	Temperature coefficient of effective permeability	1/K
r	Relative permittivity	
Þ	Magnetic flux	Vs
1	Efficiency of a transformer	
В	Hysteresis material constant	mT-1
li	Hysteresis core constant	$A^{-1}H^{-1/2}$
'S	Magnetostriction at saturation magnetization	
,	Relative complex permeability	
0	Magnetic field constant	Vs/Am
a	Relative amplitude permeability	
app	Relative apparent permeability	
е	Relative effective permeability	
i	Relative initial permeability	
p	Relative real (inductive) component of $\overline{\mu}$ (for parallel components)	
p	Relative imaginary (loss) component of $\overline{\mu}$ (for parallel components)	
r	Relative permeability	
rev	Relative reversible permeability	
S S	Relative real (inductive) component of $\overline{\mu}$ (for series components)	
s S	Relative imaginary (loss) component of $\overline{\mu}$ (for series components)	
tot	Relative total permeability	
	derived from the static magnetization curve	
	Resistivity	Ω m $^{-1}$
I/A	Magnetic form factor	mm ⁻¹
Cu	DC time constant $\tau_{Cu} = L/R_{Cu} = A_L/A_R$	s
)	Angular frequency; $\omega = 2 \Pi f$	s ⁻¹

All dimensions are given in mm.





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